

AMENDMENTS TO THE CLAIMS

1 (original). A conductive paste comprising:
a conductive component;
a glass frit comprising a $\text{Bi}_2\text{O}_3\text{-B}_2\text{O}_3\text{-SiO}_2\text{-Al}_2\text{O}_3$ or $\text{Bi}_2\text{O}_3\text{-B}_2\text{O}_3\text{-SiO}_2\text{-Al}_2\text{O}_3\text{-ZnO}$ glass as primary component and about 0.5 to 5% by weight of NiO as a secondary component; and
an organic vehicle.

2 (original). A conductive paste according to claim 1, wherein the glass contains about 60 to 85% by weight of Bi_2O_3 , about 3 to 10% by weight of B_2O_3 , about 2 to 15% by weight of SiO_2 , about 3 to 7% by weight of Al_2O_3 , and 0 to about 15% by weight of ZnO.

3 (original). A conductive paste according to claim 2, wherein the conductive component is at least one of silver, silver-palladium, platinum, gold, and rhodium.

4 (currently amended). A conductive paste according to claim 3, further comprising about 2% by weight or less of an additional paste component which is at least one of alumina, amorphous silica and MoSi_2 .

5 (original). A conductive paste according to claim 4, wherein the conductive component is a metal powder having a mean particle size of less than about 20 μm .

6 (original). A conductive paste according to claim 5, wherein the metal powder has a mean particle size of about 0.1 to 10 μm .

7 (original). A conductive paste according to claim 6, wherein the metal powder has a mean particle size of about 0.1 to 6 μm .

8 (original). A conductive paste according to claim 1, wherein the conductive component is at least one of silver, silver-palladium, platinum, gold, and rhodium.

9 (currently amended). A conductive paste according to claim 1, further comprising about 2% by weight or less of an additional paste component which is at least one of alumina, amorphous silica and MoSi₂.

10 (original). A conductive paste according to claim 1, wherein the conductive component is a metal powder having a mean particle size of less than about 20 μm.

11 (original). A conductive paste according to claim 10, wherein the metal powder has a mean particle size of about 0.1 to 10 μm.

12 (original). A conductive paste according to claim 10, wherein the metal powder has a mean particle size of about 0.1 to 6 μm.

13 (canceled).

14 (original). A conductive paste according to claim 1, disposed on a glass substrate in a conductor circuit pattern.

15 (original). A glass circuit structure comprising:

a glass substrate; and

a conductor circuit comprising a conductor film on the glass substrate;

wherein the conductor film is a baked conductive paste according to claim

1.

16 (original). A glass circuit structure according to claim 15, wherein the glass substrate is a defogging glass of an automobile window.

17 (original). A glass circuit structure comprising:

a glass substrate; and

a conductor circuit comprising a conductor film on the glass substrate;

wherein the conductor film is a baked conductive paste according to claim

4.

18 (original). A glass circuit structure according to claim 15, wherein the glass substrate is a defogging glass of an automobile window.

19 (original). A glass circuit structure comprising:

a glass substrate; and

a conductor circuit comprising a conductor film on the glass substrate;

wherein the conductor film is a baked conductive paste according to claim 5.

20 (original). A glass circuit structure according to claim 19, wherein the glass substrate is a defogging glass of an automobile window.